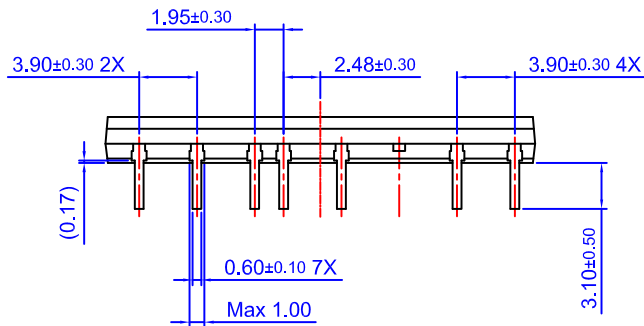
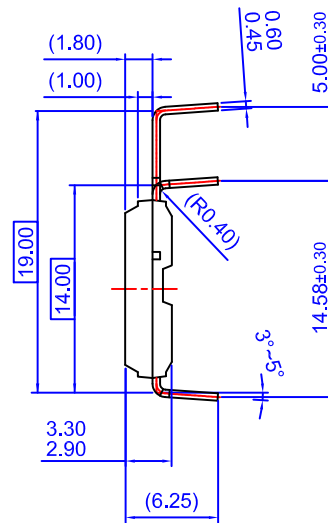
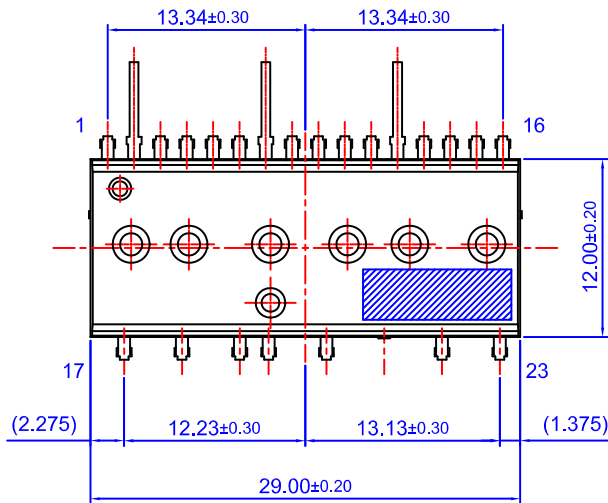
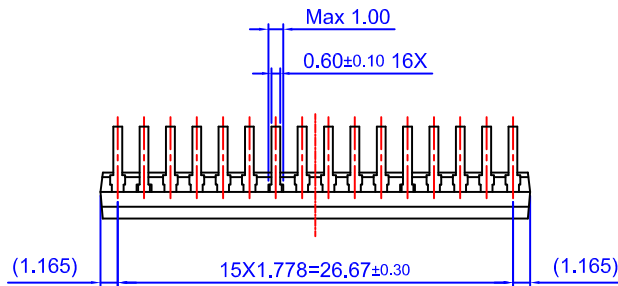


MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



SPM5F-023 / 23LD, PDD STD, FULL PACK, DOUBLE DIP TYPE
CASE MODEK
ISSUE O

DATE 31 JAN 2017



NOTES: UNLESS OTHERWISE SPECIFIED
 A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
 B) ALL DIMENSIONS ARE IN MILLIMETERS
 C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
 D) () IS REFERENCE

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NEW STANDARD:		
DESCRIPTION:	SPM5F-023 / 23LD, PDD STD, FULL PACK, DOUBLE DIP TYPE	PAGE 1 OF 2

